

Title (en)

Electrical resistor in the form of a surface mounting chip and process for making the same.

Title (de)

Elektrischer Widerstand in Chip-Bauweise für Oberflächenbestückung und Verfahren zu seiner Herstellung.

Title (fr)

Résistance électrique sous forme de puce à montage de surface et son procédé de fabrication.

Publication

**EP 0424254 B1 19940105 (FR)**

Application

**EP 90402915 A 19901017**

Priority

FR 8913759 A 19891020

Abstract (en)

[origin: EP0424254A1] The electrical resistor in chip form is intended to be soldered in particular onto a printed circuit board or onto a hybrid circuit substrate. It comprises an insulating electrical substrate (1) of the ceramic type, onto which is tied a metal or resistive alloy sheet (3) by an adhesive layer of organic resin (2). <??>The resin layer (6) leaves free, in the vicinity of two opposite edges of the substrate (1), two end portions (5) of the stamped resistive sheet (3). These two portions (5) of the resistive sheet are each covered by a thin layer (8) of a metal or alloy adhering to the resistive sheet (3), this layer (8) being covered by a second thicker layer (9) of metal or conducting alloy, and this second layer (9) being covered with a third, likewise thicker, layer (14) of a solderable alloy, these three stacked layers (8, 9, 14) also extending over the two opposing lateral faces of the substrate (1) and partially over that face (13) of the substrate opposite the stamped resistive sheet (3). <??>Use in particular in printed or hybrid circuits. <IMAGE>

IPC 1-7

**H01C 1/142**; **H01C 17/28**; **H01C 13/02**

IPC 8 full level

**H01C 1/142** (2006.01); **H01C 3/12** (2006.01); **H01C 7/00** (2006.01); **H01C 13/02** (2006.01); **H01C 17/00** (2006.01); **H01C 17/06** (2006.01); **H01C 17/28** (2006.01)

CPC (source: EP KR US)

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